

UBM Application



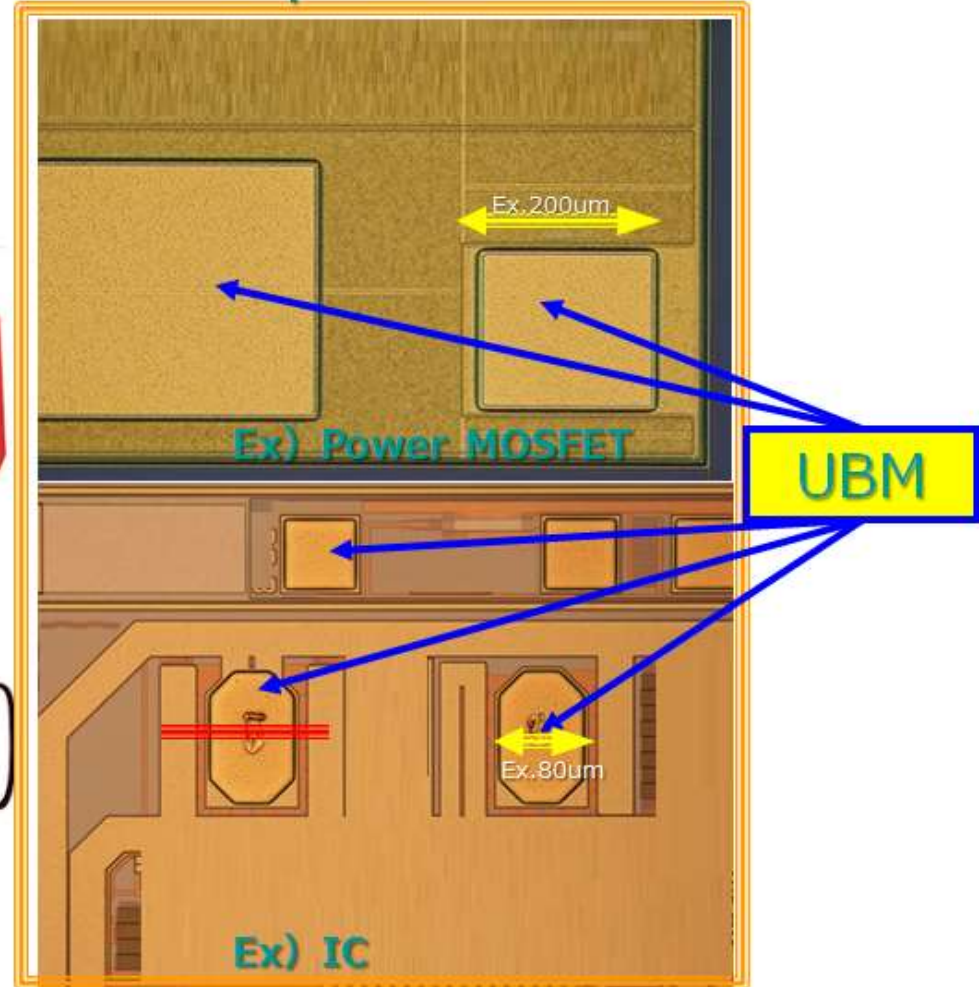
Wafer



Cross Section After Solder Mount



Chip



Key Factors of UBM-Demand

- ① Miniaturization
- ② Low RON
- ③ Heat Dissipation
- ④ Speeding Up

Ex.) Power MOSFET



Why UBM?



- ① Barrier to prevent Solder diffusion into Metal Electrode.
- ② Improvement at Solder joint.

Solder Joint

